PCN Number: 20180611003		PCN Date:	PCN Date: June 14, 2018		
Title: Datasheet for LMT01					
Customer Contact:	CN Manager		Dept:	Quality Services	
Change Type:					
Assembly Site	Desig		Waf	er Bump Site	
		Sheet		er Bump Material	
Assembly Materials		number change		er Bump Process	
Mechanical Specifica				er Fab Site	
Packing/Shipping/La	ibeling Test	Process		er Fab Materials	
Notification Details Wafer Fab Process					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification.					
The product datasheet(s) is being updated as summarized below.					
The following change history provides further details.					
ŢEXAS					
INSTRUMENTS LMT01 SNIS189D – JUNE 2015 – REVISED JUNE 2018					
Changes from Revision C (June 2017) to Revision D					
- Added device stamp to the TO 02 pinout ten view					
Added device stamp to the TO-92 pinout top view					
Changed the TO-92S pin numbers in the Pin Functions					
The datasheet number will be changing.					
Device Family		Change From:	Chan	ge To:	
LMT01		SNIS189C	SNIS	S189D	
These changes may be reviewed at the datasheet links provided.					
http://www.ti.com/product/LMT01					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes					
to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
LMT01DQXR	LMT01DQXT	LMT01LPG		LMT01LPGM	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com